

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (withdrawn, currently amended): A lithographic method of providing at least one side surface of a substrate with electrical wiring comprising at least one electrically conducting strip, which method comprises the steps of:

- providing a substrate comprising at least one side surface;
- coating the at least one side surface with a resist layer;
- providing a mask comprising a mask pattern having a number of exposure radiation passing areas corresponding to the number of side surfaces to be wired;
- providing a proximity printing apparatus comprising a source of exposure radiation, a mask holder and a substrate holder;

- arranging the substrate in the substrate holder and the mask in the mask holder, such that the radiation passing areas of the mask pattern face the substrate side surfaces to be wired;
- exposing the said surfaces via the radiation passing area;
- selectively removing resist material from the resist layer thereby forming a resist pattern, and
- using the resist pattern as a mask for configuring conductive material to obtain the required wiring, ~~characterized in that~~wherein use is made of an exposure beam, which is ~~substantially perpendicular to the mask pattern and of a mask pattern wherein each~~ at least one of the exposure radiation passing areas comprises a diffraction structure to diffract exposure radiation to the relevant substrate surface.

Claim 2 (withdrawn, currently amended): ~~A~~ The method as ~~claimed in of~~ claim 1, ~~characterized in that~~wherein use is made of a mask pattern wherein the diffraction structure is an amplitude structure.

Claim 3 (withdrawn, currently amended): ~~A~~The method as ~~elaimed inof~~ claim 1, ~~characterized in that~~wherein use is made of a mask pattern wherein the diffraction structure is a phase structure.

Claim 4 (withdrawn, currently amended): ~~The~~A method as ~~elaimed inof~~ claim 3, ~~characterized in that~~wherein use is made of a mask pattern wherein the phase structure has a duty cycle of 50% and a phase depth of 180° .

Claim 5 (withdrawn, currently amended): ~~The~~A method as ~~elaimed inof~~ claim 1, ~~characterized in that~~wherein use is made of a mask pattern wherein the diffraction structure is designed to deflect incident exposure radiation at an angle of substantially 20° to the normal to the plane of the diffraction structure.

Claim 6 (withdrawn, currently amended): ~~The~~A method as ~~elaimed inof~~ claim 1, ~~characterized in that~~wherein use is made of a mask pattern which comprises, next to a diffraction structure, mask features corresponding to

substrate features to be configured in a substrate upper surface layer.

Claim 7 (currently amended): A mask ~~for use with the method as claimed in claim 1, characterized by~~ having a mask pattern which comprises at least one diffraction structure for deflecting incident radiation in a plane comprising the direction of periodicity of the diffraction structure and the propagation direction of the incident radiation.

Claim 8 (currently amended): ~~The~~A mask ~~as claimed in of claim 7, characterized in that~~wherein the diffraction structure is an amplitude structure.

Claim 9 (currently amended): ~~The~~A mask ~~as claimed in of claim 7, characterized in that~~wherein the diffraction structure is a phase structure.

Claim 10 (currently amended): ~~The~~A mask ~~as claimed in of claim 9, characterized in that~~wherein the phase structure has a duty cycle of 50% and a phase depth of 180° .

Claim 11 (currently amended): ~~The~~A mask ~~as claimed in~~of
claim 7, ~~characterized in that~~wherein the diffraction
structure is designed to deflect incident exposure
radiation at an angle of substantially 20° to the normal
to the grating surface.

Claim 12 (currently amended): ~~The~~A mask ~~as claimed in~~of
claim 7, ~~characterized in that~~wherein its ~~the~~ mask
pattern of the mask comprises, next to a diffraction
structure, mask features corresponding to substrate
features to be configured in a substrate upper surface
layer

Claim 13 (currently amended): ~~The~~A mask ~~as claimed in~~of
claim 7, ~~characterized in that~~wherein the diffraction
structure is a linear diffraction grating.

Claim 14 (currently amended): ~~The~~A mask ~~as claimed in~~of
claim 7, ~~characterized in that~~wherein the diffraction
structure is a two-dimensional diffraction grating.

Claim 15 (currently amended): ~~The~~A mask ~~as claimed in~~of claim 7, ~~characterized in that~~wherein the diffraction structure comprises a number of linear diffraction gratings, which each form a segment of a common circular area.

Claim 16 (withdrawn, currently amended): A device comprising a substrate, which forms a carrier for at least one electronic component and has a wiring on at least one side end surface, manufactured by means of the method ~~as claimed in~~of claim 1.

Claim 17 (new): A mask having a mask pattern which comprises at least one diffraction structure for deflecting incident radiation in a plane comprising the direction of periodicity of the diffraction structure and the propagation direction of the incident radiation, the diffraction structure corresponding to a substrate feature to be configured in a substrate side surface layer.